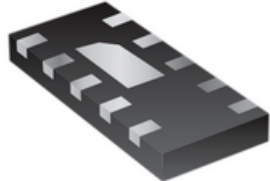


# MATERIAL DECLARATION SHEET



Material Number	CDDFN10-0516P			
Product Line	Semiconductor Products			
Compliance Date	8 Jan 2016			
RoHS Compliant	Yes	MSL	3	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Wafer	Silicon	1.0	Silicon	7440-21-3	100.00%	9.5238%	9.5238%
2	Lead Frame	Copper alloy	3.896	Copper	7440-50-8	97.400%	37.1048%	38.0953%
			0.092	Iron	7439-89-6	2.300%	0.8762%	
			0.004	Phosphorus	7723-14-0	0.100%	0.0381%	
			0.004	Zinc	7440-66-6	0.100%	0.0381%	
			0.0008	Lead	7439-93-1	0.020%	0.0076%	
			0.0032	Silver	7440-22-4	0.080%	0.0305%	
3	Epoxy	Polymer	0.22	Silica, crystalline	14808-60-7	44.00%	2.0952%	4.7618%
			0.21	Epoxy resin	Proprietary	42.00%	2.0000%	
			0.06	Epoxy resin modifier	Proprietary	12.00%	0.5714%	
			0.01	Amine	Proprietary	2.00%	0.0952%	

# MATERIAL DECLARATION SHEET



4	Gold Wire	Noble metal	0.49995	Gold	7440-57-5	99.99%	4.7614%	4.7619%
			0.00005	Others not to declare	/	0.01%	0.0005%	
5	Mold Compound	Polymer	0.08	Epoxy resin 1	trade secret	2.00%	0.7619%	38.0953%
			0.08	Epoxy resin 2	trade secret	2.00%	0.7619%	
			0.08	Epoxy resin 3	trade secret	2.00%	0.7619%	
			0.12	Phenol Resin	trade secret	3.00%	1.1429%	
			0.004	Carbon Black	1333-86-4	0.10%	0.0381%	
			3.596	Amorphous silica	60676-86-0	89.90%	34.2476%	
			0.04	Crystalline silica	14808-60-7	1.00%	0.3810%	
6	Plating	plating	0.49995	Tin	7440-31-5	99.99%	4.7614%	4.7619%
			0.00005	Others not to declare	/	0.01%	0.0005%	
<b>Total weight</b>			10.5					

**This Document was updated on: 2015/12/03**

**Important remarks:**

1. It is the responsibility of the user to verify they are accessing the latest version.